PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4896078

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Wei-Lun Hsu	03/23/2018
Hung-Lin Shih	03/23/2018
Che-Hung Huang	03/23/2018
Ping-Cheng Hsu	03/23/2018
Hsu-Yang Wang	03/23/2018

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN
Name:	FUJIAN JINHUA INTEGRATED CIRCUIT CO., LTD.
Street Address:	NO.88, LIANHUA AVENUE, INTEGRATED CIRCUIT SCIENCE PARK, JINJIANG CITY
City:	QUANZHOU CITY, FUJIAN PROVINCE
State/Country:	CHINA

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15943721

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	NAUP3251USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/

PATENT 504849340 REEL: 045420 FRAME: 0146

DATE SIGNED:	04/03/2018
Total Attachments: 10	
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PATENT REEL: 045420 FRAME: 0147

Title of Invention:

SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application nu	mber	filed o	on	, or
☐ PCT international application	n number	file	d on	
The above-identified application was	s made or authorized t	be made by me.		
I believe that I am the original invent application.	or or an original joint i	nventor of a claime	d invention in the	e
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	Il false statement mad risonment of not more	e in this declaration than five (5) years,	is punishable or both.	
In consideration of the payment by	UNITED MICROE CORP.	LECTRONICS	having a postal	l address of
No.3, Li-Hsin Road 2, Science	-Based Industrial	Park, Hsin-Chu	City 300, Tai	wan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One I nd valuable considerat	Pollar (\$ 1.00), the ion.	receipt of which i	is hereby
In consideration of the payment by	Fujian Jinhua Into Co., Ltd.	egrated Circuit	having a postal	address of
No.88, Lianhua Avenue, Integ Fujian Province 362200, P.R.O	rated Circuit Scie	nce Park, Jinjia	ng City, Quan	zhou City,
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I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all impro ition and, in and to, all r any continuations. co	vements which are Letters Patent to b ntinuation-in-part.	e disclosed in the e obtained for sa divisions, renewa	id als
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or h this assignment;	encumbrance has	been or will be m	nade or
I further covenant that ASSIGNEE wand documents relating to said inverknown and accessible to I and will te related thereto and will promptly exe	ntion and said Letters I estify as to the same in	Patent and legal eq any interference, l	uivalents as may itigation proceed	/ be

Page 1 of 10

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WITNESS WHEREOF, I have hereunto set hand and seal this MAR 2 3 2018 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

Inventor: Wei-Lun Hsu Date: MAR 2 3 2018.

Signature: Wei - Lun Hsu

Page 2 of 10

Title of Invention:

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The above-identified application was	made or authorized to	be made by me.		
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I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all impro ition and, in and to, all l r any continuations, co	vements which are _etters Patent to b ntinuation-in-part. (e disclosed in the e obtained for said divisions, renewals	
I hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or on this assignment;	encumbrance has	been or will be mad	le or
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Page 3 of 10

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WITNESS WHEREOF, I have hereunto set hand and seal this MAR 2 3 2018 (Date of signing)

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Hung-Lin Shih Date: MAR 2 3 2018

Signature: MAR 2 3 2018

Page 4 of 10

Title of Invention:

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The above-identified application was	s made or authorized to be made	by me.	A Market A	
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In consideration of the payment by	UNITED MICROELECTROI CORP.	NICS	having a postal addr	ess of
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No.88, Lianhua Avenue, Integ Fujian Province 362200, P.R.0	rated Circuit Science Park, C.	, Jinjiar	ng City, Quanzhou	ı City,
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I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application o substitutes, or extensions thereof, an	nd to any and all improvements w ation and, in and to, all Letters Par r any continuations, continuation-	which are tent to be in-part, o	disclosed in the obtained for said livisions, renewals.	E
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Page 5 of 10

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representatives any and all papers, instruments or maintain, issue and enforce said application, said in equivalents thereof which may be necessary or des IN WITNESS WHEREOF, I have hereunto set hand	nvention and said Letters sirable to carry out the pr	Patent and	, said
Note: An application data sheet (PTO/SB/14 or equinventive entity, must accompany this form. Use this			,
LEGAL NAME OF INVENTOR(ASSIGNOR)			
Inventor: Che-Hung Huang	Date:		MAR 2 3 2018

Title of Invention:

SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

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F#NPO-P0002E-US1201 DSB0-107U002357 representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WITNESS WHEREOF, I have hereunto set hand and seal this MAR 2 3 2018 (Date of signing)

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Ping-Cheng Hsu Date: MAR 2 3 2018

Page 8 of 10

Title of Invention:

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Docket No NAUP3251USA

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LEGAL NA	INIE OF INVENTOR(ASSIGNOR)		
Inventor:	Hsu-Yang Wang	Date:	MAR 2 3 2018
Signature:	Man - Yang Wang		, ,
	0 ()		

10 of Page 10

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PATENT REEL: 045420 FRAME: 0157

RECORDED: 04/03/2018